

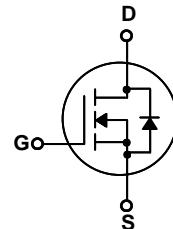
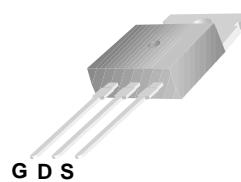

Wisdom Technologies Int'l

WFP12N60

600V N-Channel MOSFET

Features

- Low Intrinsic Capacitances
- Excellent Switching Characteristics
- Extended Safe Operating Area
- Unrivalled Gate Charge : $Q_g = 37\text{nC}$ (Typ.)
- $V_{DSS} = 600\text{V}, I_D = 12\text{A}$
- $R_{DS(on)} : 0.65 \Omega$ (Max) @ $V_G = 10\text{V}$
- 100% Avalanche Tested


TO-220
G-Gate,D-Drain,S-Source

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	WFP12N60	Units
V_{DSS}	Drain-Source Voltage	600	V
I_D	Drain Current -continuous ($T_c=25^\circ\text{C}$)	12	A
	-continuous ($T_c=100^\circ\text{C}$)	6.7	A
V_{GS}	Gate-Source Voltage	± 30	V
E_{AS}	Single Plused Avalanche Energy (Note1)	870	mJ
I_{AR}	Avalanche Current (Note2)	12	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	225	W
T_J, T_{STG}	Operating and Storage Temperature Range	-55 ~ +150	°C
T_L	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max	Units
$R_{\theta JC}$	Thermal Resistance,Junction to Case	--	0.7	°C/W
$R_{\theta CS}$	Thermal Resistance,Case to Sink	0.5	--	°C/W
$R_{\theta JA}$	Thermal Resistance,Junction to Ambient	--	62.5	°C/W

Electrical Characteristics $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Typ.	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{ID}=250 \mu\text{A}, \text{VGS}=0$	600	--	--	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Breakdown Voltage Temperature Coefficient	$\text{I}_D=250 \mu\text{A}, \text{Reference to } 25^\circ\text{C}$	--	0.71	--	V/ $^\circ\text{C}$
IDSS	Zero Gate Voltage Drain Current	$\text{V}_{\text{DS}}=600\text{V}, \text{V}_{\text{GS}}=0\text{V}$	--	--	10	μA
		$\text{V}_{\text{DS}}=480\text{V}, \text{Tc}=125^\circ\text{C}$			100	μA
IGSSF	Gate-body leakage Current, Forward	$\text{V}_{\text{GS}}=+30\text{V}, \text{V}_{\text{DS}}=0\text{V}$	--	--	100	nA
IGSSR	Gate-body leakage Current, Reverse	$\text{V}_{\text{GS}}=-30\text{V}, \text{V}_{\text{DS}}=0\text{V}$	--	--	-100	nA

On Characteristics

$\text{V}_{\text{GS(th)}}$	Date Threshold Voltage	$\text{Id}=250\mu\text{A}, \text{V}_{\text{DS}}=\text{V}_{\text{GS}}$	2	--	4	V
$\text{R}_{\text{DS(on)}}$	Static Drain-Source On-Resistance	$\text{Id}=6\text{A}, \text{V}_{\text{GS}}=10\text{V}$	--	--	0.65	Ω

Dynamic Characteristics

Ciss	Input Capacitance	VDS=25V, VGS=0, f=1.0MHz	--	1480	1900	pF
Coss	Output Capacitance		--	200	270	pF
Crss	Reverse Transfer Capacitance		--	25	35	pF

Switching Characteristics

Td(on)	Turn-On Delay Time	VDD=300V, ID=12A RG=25Ω (Note 3,4)	--	30	70	nS
Tr	Turn-On Rise Time		--	115	240	nS
Td(off)	Turn-Off Delay Time		--	95	200	nS
Tf	Turn-Off Fall Time		--	85	180	nS
Qg	Total Gate Charge	VDS=480,VGS=10V, ID=12A (Note 3,4)	--	42	54	nC
Qgs	Gate-Source Charge		--	8.6	--	nC
Qgd	Gate-Drain Charge		--	21	--	nC

Drain-Source Diode Characteristics and Maximum Ratings

I_S	Maximum Continuous Drain-Source Diode Forward Current	--	--	12	A	
I_{SM}	Maximum Plused Drain-Source DiodeForward Current	--	--	48	A	
V_{SD}	Drain-Source Diode Forward Voltage	$\text{Id}=12\text{A}$	--	--	1.4	V
trr	Reverse Recovery Time	$\text{I}_S=12\text{A}, \text{V}_{\text{GS}}=0\text{V}$	--	380	--	nS
Qrr	Reverse Recovery Charge	$\text{di}_f/\text{dt}=100\text{A}/\mu\text{s}$ (Note3)	--	3.5	--	μC

*Notes 1, L=11.1mH, IAS=12A, VDD=50V, RG=25Ω, Starting TJ =25°C

2, Repetitive Rating : Pulse width limited by maximum junction temperature

3, Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%

4, Essentially Independent of Operating Temperature

Typical Characteristics

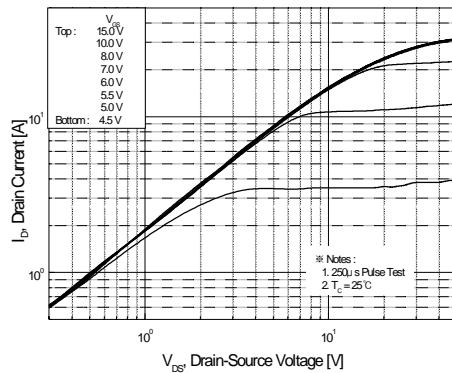


Figure 1. On-Region Characteristics

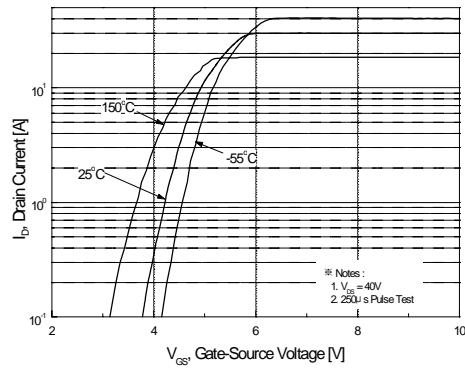


Figure 2. Transfer Characteristics

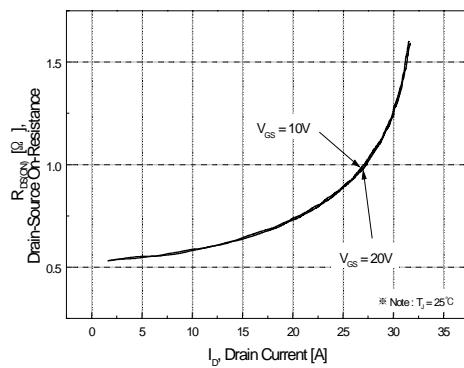


Figure 3. On-Resistance Variation vs
Drain Current and Gate Voltage

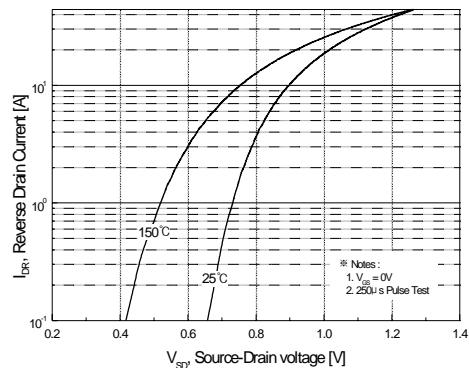


Figure 4. Body Diode Forward Voltage
Variation with Source Current
and Temperature

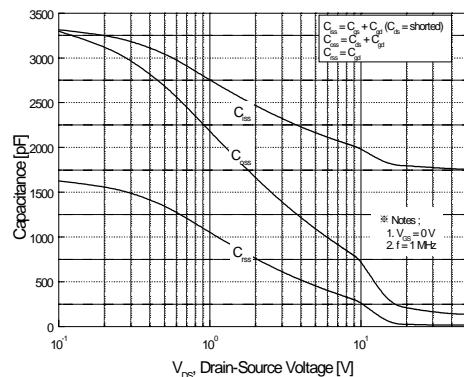


Figure 5. Capacitance Characteristics

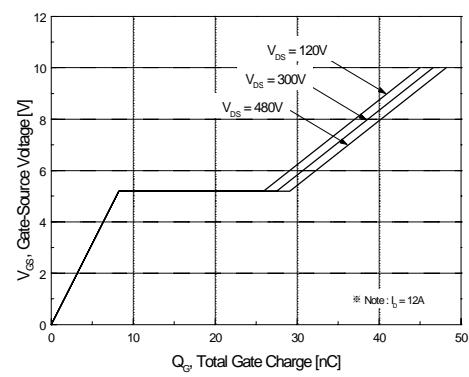


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

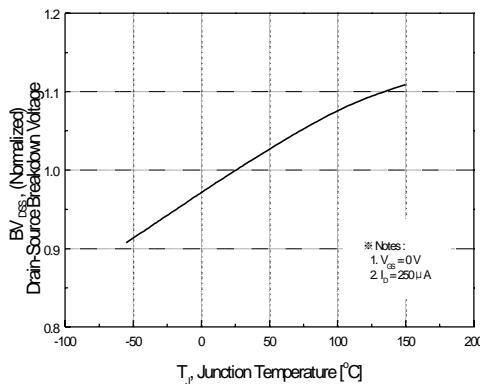


Figure 7. Breakdown Voltage Variation vs Temperature

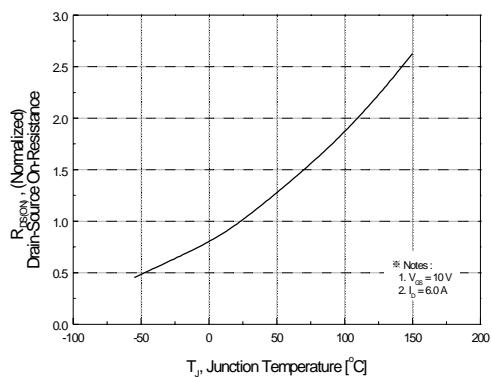


Figure 8. On-Resistance Variation vs Temperature

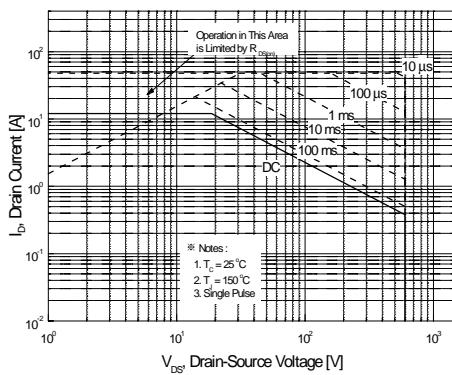


Figure 9-1. Maximum Safe Operating Area for WFP12N60

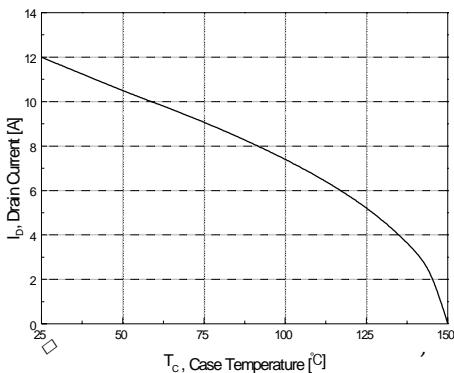


Figure 10. Maximum Drain Current vs Case Temperature

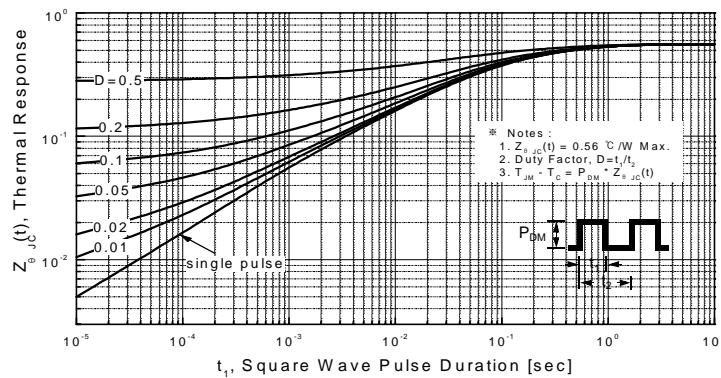
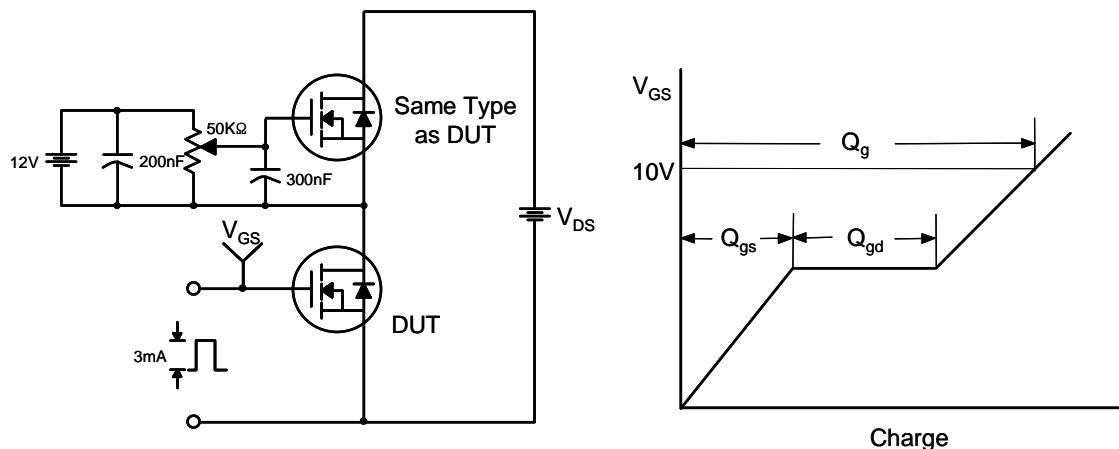
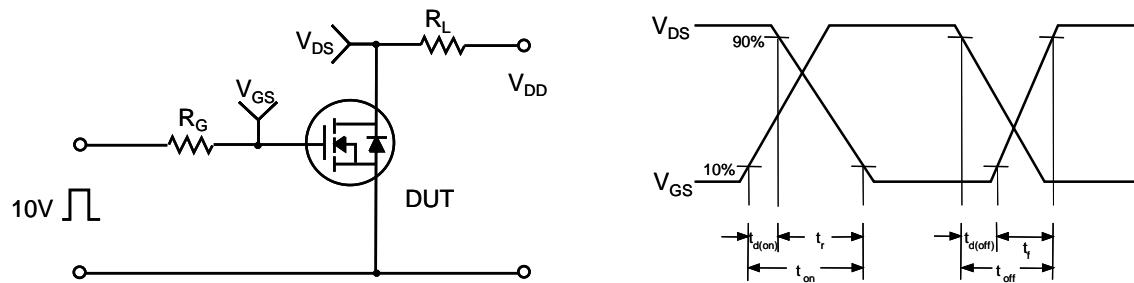
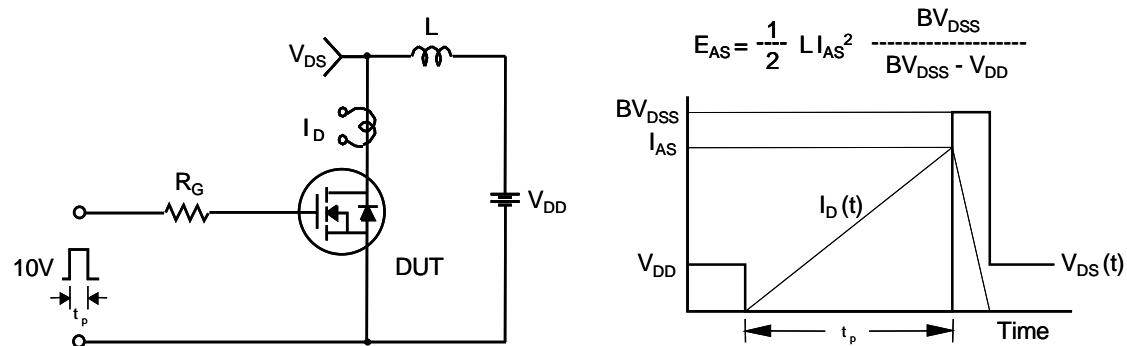


Figure 11-1. Transient Thermal Response Curve for WFP12N60

Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

Unclamped Inductive Switching Test Circuit & Waveforms


Peak Diode Recovery dv/dt Test Circuit & Waveforms

